

## **AGENDA**

### **SOLDERING TECHNOLOGY COMMITTEE (STC)**

**Tuesday, October 18, 2005**

**Doubletree Hotel, Memphis, TN**

#### **1) Introductions and Roster modifications**

#### **2) April meeting minutes approval**

##### **2 Old business**

##### **3 New business**

#### **3.1 Revision to IPC/EIA J-STD-002B**

##### **3.1.1 J-STD-002C Status**

Work has been completed on the DOE which evaluated Pb-free solderability parameters. The Committee ballot has been sent out and responses received. Dave Hillman will review status of J-STD-002C and timing for next steps in the process of approval.

##### **3.2 Possible replacements for steam pre-conditioning**

Committee members have agreed that an area for future work is the replacement of steam pre-conditioning. Investigation of industry data and other pre-condition methods in use will be needed. Mr. Hillman has indicated that he will support this activity.

##### **3.3 Gauge R&R for wetting balance test**

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

#### **4 Next meeting**

#### **5 Adjournment**